ALPHA & OMEGA SEMICONDUCTOR

AON7380

30V N-Channel AlphaMOS

General Description

- Trench Power AlphaMOS (αMOS LV) technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- High Current Capability
- RoHS and Halogen-Free Compliant

Applications

- DC/DC Converters in Computing
- Isolated DC/DC Converters in Telecom and Industrial
- See Note I

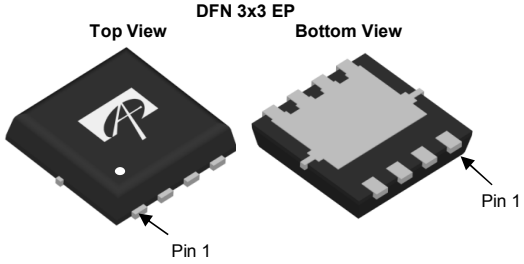
Product Summary

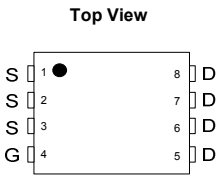
V_{DS}	30V
I_D (at V_{GS}=10V)	24A
$R_{DS(ON)}$ (at V_{GS}=10V)	< 6.8mΩ
$R_{DS(ON)}$ (at V_{GS}=4.5V)	< 10.5mΩ

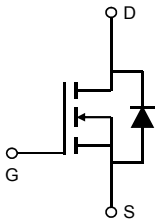
100% UIS Tested
100% Rg Tested

Green Product

DFN 3x3 EP







Orderable Part Number	Package Type	Form	Minimum Order Quantity
AON7380	DFN 3x3 EP	Tape & Reel	5000

Absolute Maximum Ratings T_A=25°C unless otherwise noted

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current [G]	T_C=25°C	I_D	24	A
	T_C=100°C		24	
Pulsed Drain Current [C]		I_{DM}	80	
Continuous Drain Current	T_A=25°C	I_{DSM}	20	A
	T_A=70°C		15	
Avalanche Current [C]		I_{AS}	60	A
Avalanche energy	L=0.001mH [C]	E_{AS}	2	mJ
V_{DS} Spike	10µs	V_{SPIKE}	36	V
Power Dissipation [B]	T_C=25°C	P_D	24	W
	T_C=100°C		9.5	
Power Dissipation [A]	T_A=25°C	P_{DSM}	4.1	W
	T_A=70°C		2.6	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	24	30	°C/W
Maximum Junction-to-Ambient [A D]	Steady-State		47	60	°C/W
Maximum Junction-to-Case	Steady-State	$R_{\theta JC}$	4.2	5.2	°C/W

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	ID=250µA, VGS=0V	30			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=30V, V_{GS}=0V			1	µA
		T_J=55°C			5	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}=±20V			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=$V_{GS,}$ I_D=250µA	1.4	1.8	2.2	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=20A		5.6	6.8	mΩ
		T_J=125°C		8.1	9.8	
		V_{GS}=4.5V, I_D=20A		8.2	10.5	mΩ
g_{FS}	Forward Transconductance	V_{DS}=5V, I_D=20A		40		S
V_{SD}	Diode Forward Voltage	I_S=1A, V_{GS}=0V		0.7	1	V
I_S	Maximum Body-Diode Continuous Current [G]				24	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=15V, f=1MHz		825		pF
C_{oss}	Output Capacitance			335		pF
C_{rss}	Reverse Transfer Capacitance			40		pF
R_g	Gate resistance	f=1MHz	0.6	1.2	1.8	Ω
SWITCHING PARAMETERS						
Q_g(10V)	Total Gate Charge	V_{GS}=10V, V_{DS}=15V, I_D=20A		13	25	nC
Q_g(4.5V)	Total Gate Charge			6.2	12	nC
Q_{gs}	Gate Source Charge			2.2		nC
Q_{gd}	Gate Drain Charge			2.6		nC
Q_{gs}	Gate Source Charge	V_{GS}=4.5V, V_{DS}=15V, I_D=20A		2.2		nC
Q_{gd}	Gate Drain Charge			2.6		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{DS}=15V, R_L=0.75Ω, R_{GEN}=3Ω		5		ns
t_r	Turn-On Rise Time			3		ns
$t_{D(off)}$	Turn-Off DelayTime			20		ns
t_f	Turn-Off Fall Time			3		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=20A, di/dt=500A/µs		11		ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=20A, di/dt=500A/µs		17		nC

A. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A =25° C. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ t≤ 10s and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design.
B. The power dissipation P_D is based on $T_{J(MAX)}$=150° C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
C. Single pulse width limited by junction temperature $T_{J(MAX)}$=150° C.
D. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.
E. The static characteristics in Figures 1 to 6 are obtained using <300µs pulses, duty cycle 0.5% max.
F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}$=150° C. The SOA curve provides a single pulse rating.
G. The maximum current rating is package limited.
H. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C.
I. For application requiring slow >1ms turn-on/turn-off, please consult AOS FAE for proper product selection.

THIS PRODUCT HAS BEEN DESIGNED AND QUALIFIED FOR THE CONSUMER MARKET. APPLICATIONS OR USES AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS ARE NOT AUTHORIZED. AOS DOES NOT ASSUME ANY LIABILITY ARISING OUT OF SUCH APPLICATIONS OR USES OF ITS PRODUCTS. AOS RESERVES THE RIGHT TO IMPROVE PRODUCT DESIGN, FUNCTIONS AND RELIABILITY WITHOUT NOTICE.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

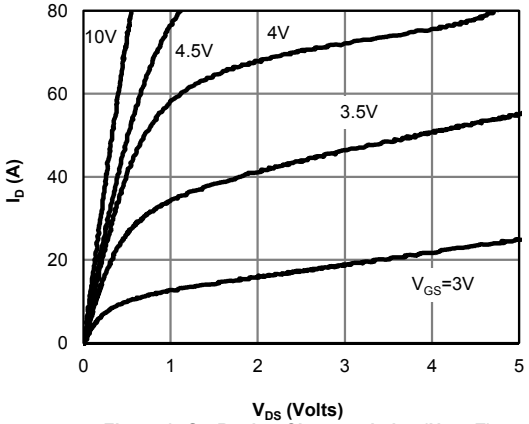


Figure 1: On-Region Characteristics (Note E)

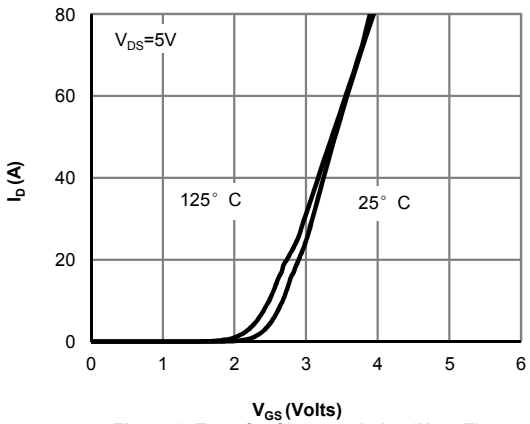


Figure 2: Transfer Characteristics (Note E)

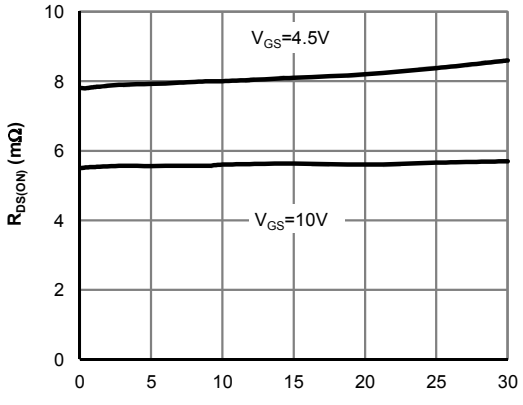


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

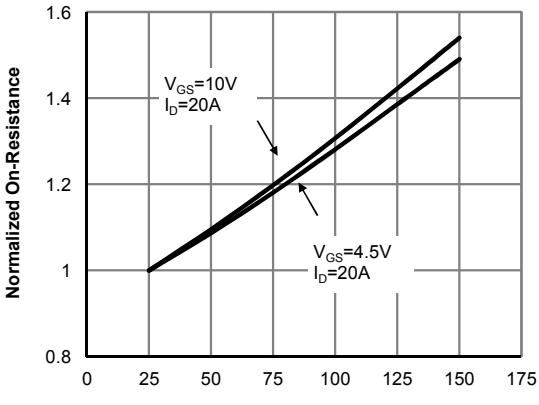


Figure 4: On-Resistance vs. Junction Temperature (Note E)

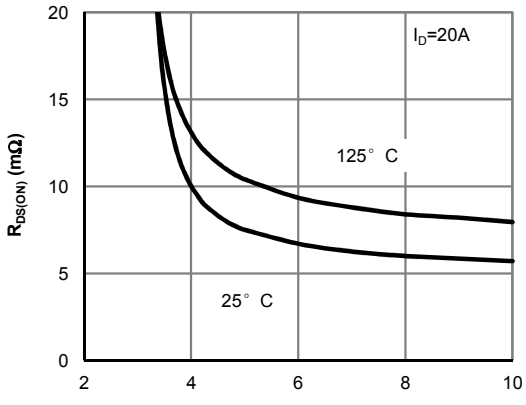


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

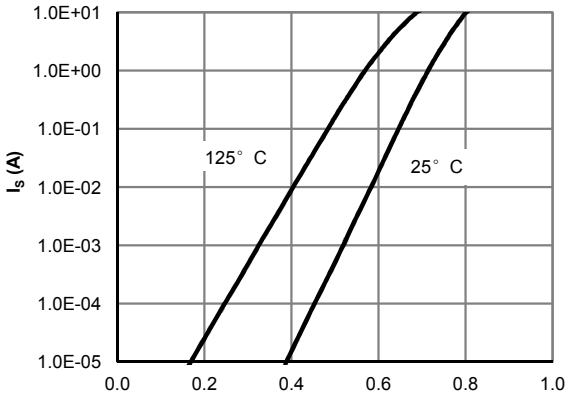


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

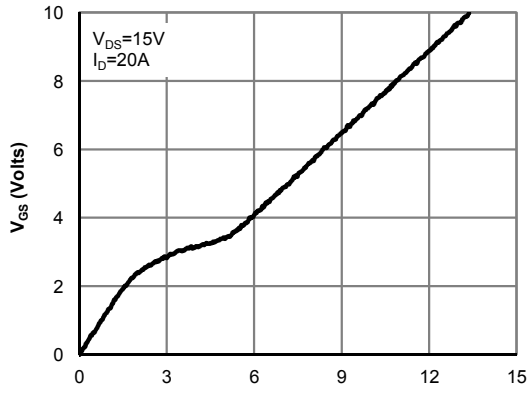


Figure 7: Gate-Charge Characteristics

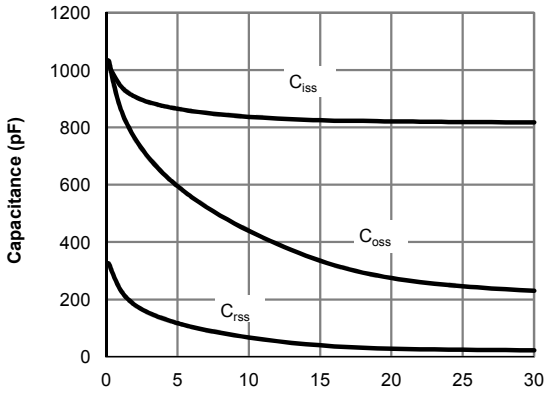


Figure 8: Capacitance Characteristics

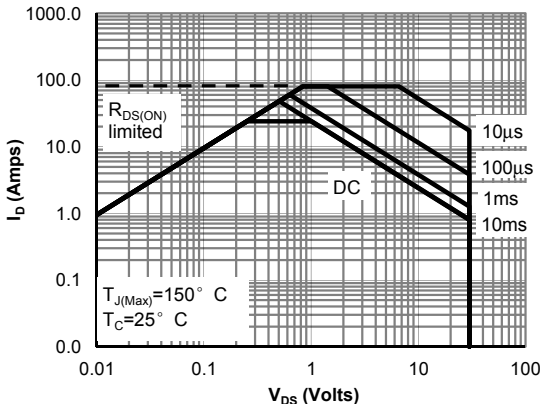


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

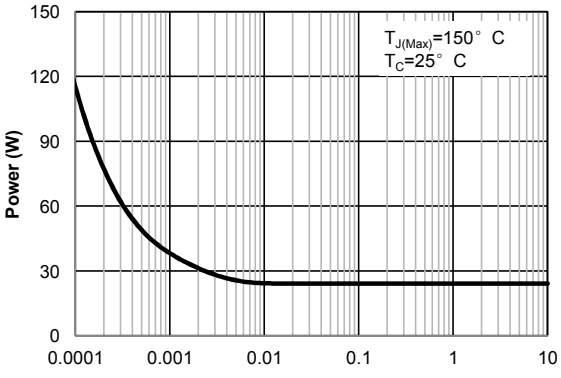


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

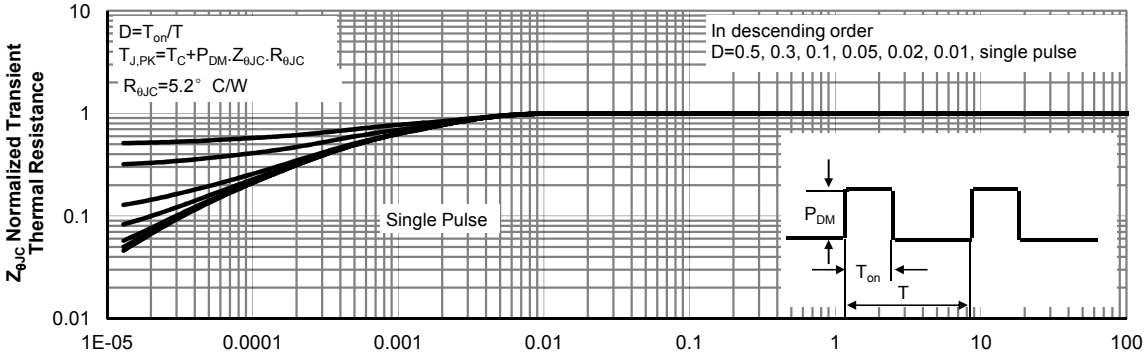


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

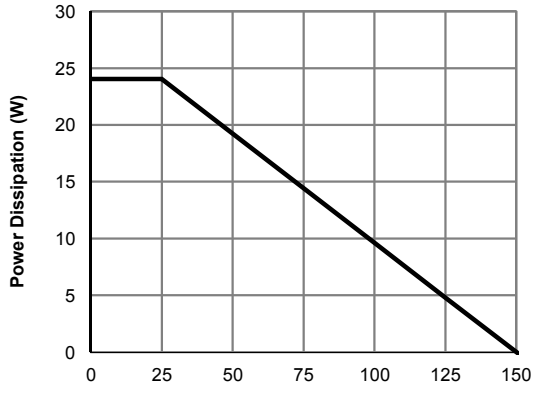


Figure 12: Power De-rating (Note F)

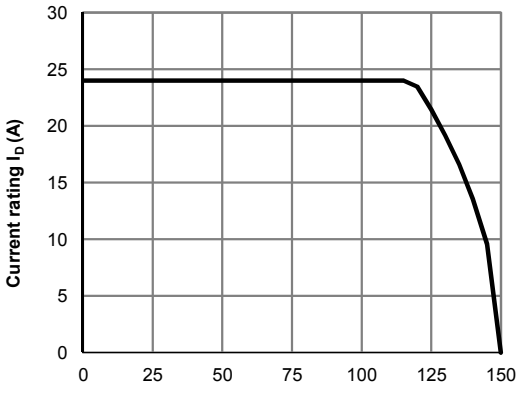


Figure 13: Current De-rating (Note F)

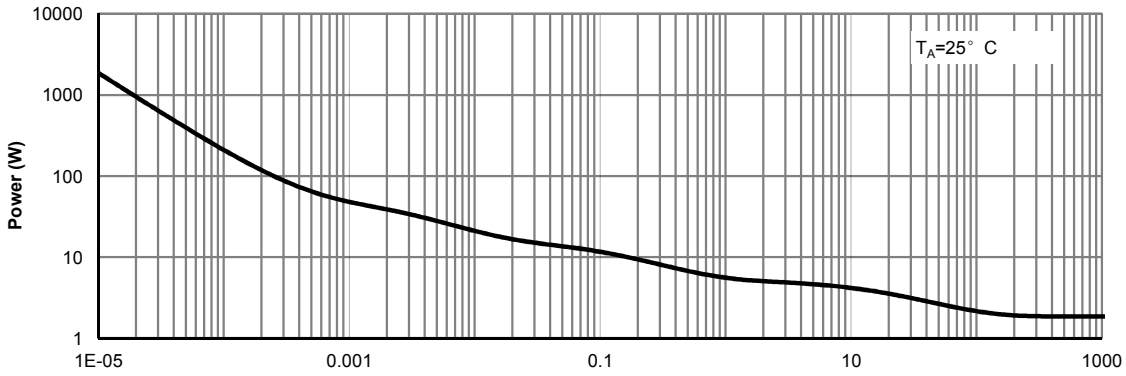


Figure 14: Single Pulse Power Rating Junction-to-Ambient (Note H)

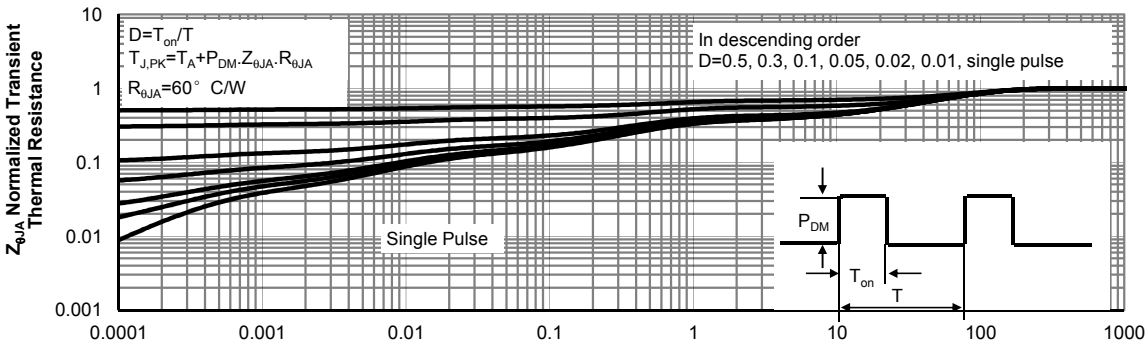


Figure 15: Normalized Maximum Transient Thermal Impedance (Note H)

Figure A: Gate Charge Test Circuit & Waveforms

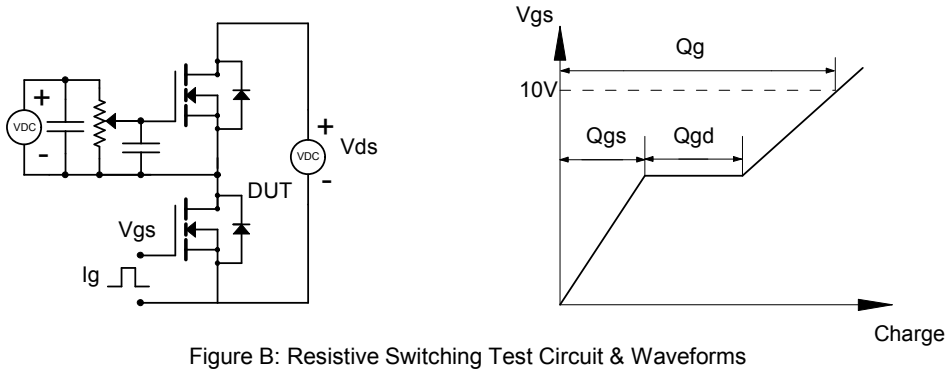


Figure B: Resistive Switching Test Circuit & Waveforms

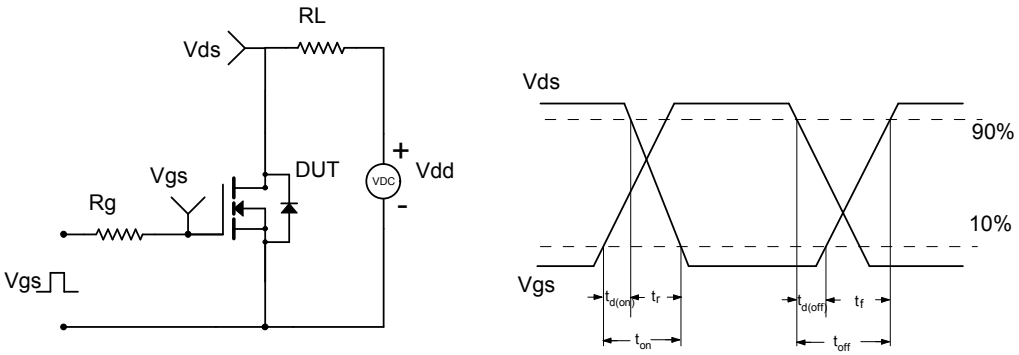


Figure C: Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

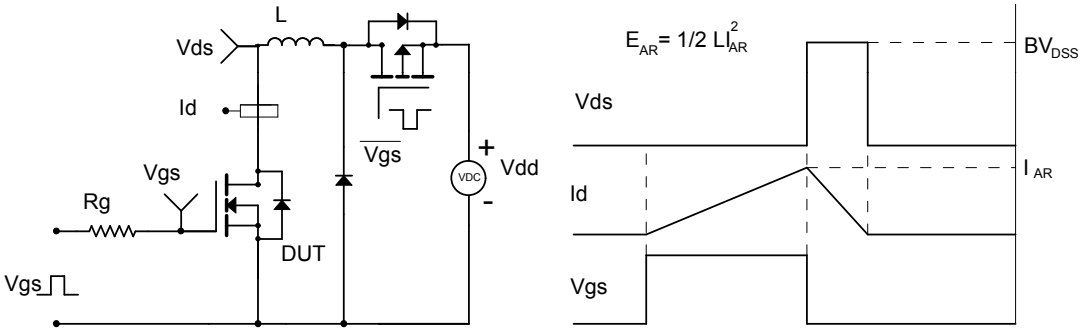


Figure D: Diode Recovery Test Circuit & Waveforms